

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A card comprising:
a display device comprising a first semiconductor element comprising a first polycrystalline semiconductor film;
a first thin film integrated circuit comprising a second semiconductor element comprising a second polycrystalline semiconductor film;
a first substrate; and
a second substrate,
wherein the display device is electrically connected to the first thin film integrated circuit,
wherein the thin film integrated circuit and the display device are covered and sealed with a resin between the first substrate and the second substrate of the card,
[[and]]
wherein the resin is in contact with the second substrate; and
wherein the first substrate and the second substrate comprise a plastic material.
2. (Original) A card according to claim 1, wherein the card has a thickness from 0.05 mm through 1.5 mm.
3. (Previously Presented) A card according to claim 1, wherein the display device is a passive matrix type display device.
4. (Original) A card according to claim 1, wherein the display device is an active matrix type.

5. (Previously Presented) A card according to claim 1, further comprising:
a second thin film integrated circuit,
wherein the first and second thin film integrated circuits are laminated.

6.-8. (Canceled)

9. (Previously Presented) A card according to claim 1, wherein the display
device is a liquid crystal display device.

10. (Canceled)

11. (Previously Presented) A card according to claim 1, wherein the display
device is a light emitting device.

12. (Canceled)

13. (Previously Presented) A card according to claim 1, wherein the card is an
ID card.

14. (Canceled)

15. (Previously Presented) A card according to claim 1, wherein the card is a
semi-hard card.

16. (Canceled)

17. (Previously Presented) A card according to claim 1, wherein the card is an IC card.

18.-19. (Canceled)

20. (Currently Amended) A card comprising:

a first substrate comprising a plastic material;

a display device comprising a first semiconductor element comprising a first polycrystalline semiconductor film over the first substrate;

a first thin film integrated circuit comprising a second semiconductor element comprising a second polycrystalline semiconductor film over the first substrate;

a resin over the display device and the first thin film integrated circuit; and

a second substrate comprising a plastic material over the resin,

wherein the resin is in contact with the second substrate.

21. (Previously Presented) A card according to Claim 5, further comprising an insulating film,

wherein the display device and one of the first and second thin film integrated circuits are in contact with the insulating film.

22. (Previously Presented) A card according to Claim 1, further comprising:

an antenna; and

an insulating film,

wherein the display device, the first thin film integrated circuit and the antenna are in contact with the insulating film.

23. (Previously Presented) A card according to Claim 1, wherein the display device comprises a third substrate.

24. (Previously Presented) A card according to claim 20, further comprising a second thin film integrated circuit comprising a third semiconductor element comprising a third polycrystalline semiconductor film;

wherein the first and second thin film integrated circuits are laminated to each other.

25. (Previously Presented) A card according to Claim 24, further comprising an insulating film,

wherein the display device and one of the first and second thin film integrated circuits are in contact with the insulating film.

26. (Previously Presented) A card according to Claim 20, further comprising:
an antenna; and
an insulating film,

wherein the display device, the first thin film integrated circuit and the antenna are in contact with the insulating film.

27. (Previously Presented) A card according to Claim 20, wherein the display device comprises a third substrate.

28. (New) A card according to Claim 1 further comprising: an adhesive below the thin film integrated circuit and the display device, and in contact with the first substrate.

29. (New) A card according to Claim 28, wherein the adhesive is a photo-curing adhesive or a light curing adhesive.

30. (New) A card according to Claim 28, wherein the adhesive includes a powder comprising one of silver, nickel, aluminum, and aluminum nitride or a filler.

31. (New) A card according to Claim 20 further comprising: an adhesive below the thin film integrated circuit and the display device, and in contact with the first substrate.

32. (New) A card according to Claim 31, wherein the adhesive is a photo-curing adhesive or a light curing adhesive.

33. (New) A card according to Claim 31, wherein the adhesive includes a powder comprising one of silver, nickel, aluminum, and aluminum nitride or a filler.